



CE65E160DNHI

CorEnergy 650V GaN HEMT

Description

The CE65E160DNHI Series 650V, 160mΩ gallium nitride (GaN) FETs are normally-off devices. Coreenergy GaN FETs offer better efficiency through lower gate charge, faster switching speeds, and smaller reverse recovery charge, delivering significant advantages over traditional silicon (Si) devices.

Coreenergy is a leading-edge wide band gap supplier with world-class innovation .

Application

- Fast charger
- Renewable energy
- Telecom and data-com
- Servo motors
- Industrial
- Automotive

General Features

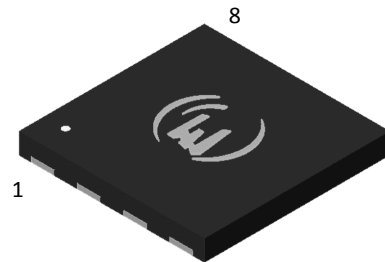
Low conduction and switching losses no free-wheeling diode required RoHS compliant and Halogen-free

Benefits

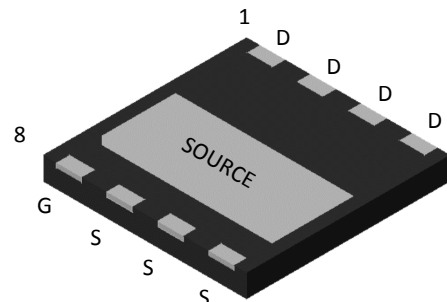
Increased efficiency through fast switching
 Increased power density
 Reduced system size and weight

Ordering Information

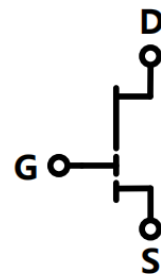
Part Number	Package	Package Configuration
CE65E160DNHI	DFN(8*8)	Source



Top



Bottom



Circuit Symbol

Features

BV_{DSS}	$R_{DS(on)}$	I_{DS}	Q_G
650V	160mΩ	13A	2.2nC



Absolute Maximum Ratings

$T_j=25^{\circ}\text{C}$ unless otherwise stated

Symbol	Parameter	Limit value	Unit	
$V_{DS,max}$	Drain to source voltage($T_j=-55^{\circ}\text{C}$ to 150°C)	650	V	
$V_{DS(transient)}$	Drain to source voltage-transient ^a	750		
V_{GS}	Gate to source voltage	-10~+7		
I_D	Continuous drain current @ $T_C=25^{\circ}\text{C}$ ^b	13	A	
	Continuous drain current @ $T_C=125^{\circ}\text{C}$ ^b	6		
I_{DM}	Pulse drain current (pulse width: 300 μs) @ $T_C=25^{\circ}\text{C}$	17		
	Pulse drain current (pulse width: 300 μs) @ $T_C=125^{\circ}\text{C}$	10		
P_D	Maximum power dissipation @ $T_C=25^{\circ}\text{C}$	64	W	
T_C	Operating temperature	Case	-55~150	$^{\circ}\text{C}$
T_J		Junction	-55~150	$^{\circ}\text{C}$
T_S	Storage temperature		-55~150	$^{\circ}\text{C}$

Notes:

a.Non-repetitive events, $T_{pulse} < 200\mu\text{s}$

b.For increased stability at high current operation

**CE65E160DNHI**

Thermal Resistance

Symbol	Parameter	Limit value	Unit
$R_{\theta JC}$	Junction-to-case	1.96	°C/W



Electrical Parameters

$T_j=25^\circ\text{C}$ unless otherwise stated

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
Forward Device Characteristics						
$V_{(BL)DSS}$	Drain-source voltage	650	-	-	V	$V_{GS}=0V$
$V_{GS(th)}$	Gate threshold voltage	2	2.5	3	V	$I_D=10\mu A/mm$, $V_{DS}=1V$, $T_j=25^\circ C$
	Gate threshold voltage	-	2.8	-	V	$I_D=10\mu A/mm$, $V_{DS}=1V$, $T_j=150^\circ C$
$R_{DS(on)}$	Drain-source on resistance	-	160	190	m Ω	$V_{GS}=6V$, $I_D=1A$, $T_j=25^\circ C$
		-	330	-		$V_{GS}=6V$, $I_D=1A$, $T_j=150^\circ C$
I_{DSS}	Drain-to-source leakage current	-	1	20	μA	$V_{DS}=650V$, $V_{GS}=0V$, $T_j=25^\circ C$
		-	10	50		$V_{DS}=650V$, $V_{GS}=0V$, $T_j=150^\circ C$
I_{GSS}	Gate-to-source forward leakage current	-	60	-	μA	$V_{GS}=6V$, $V_{DS}=0V$
C_{ISS}	Input capacitance	-	66	-	pF	$V_{GS}=0V$, $V_{DS}=400V$, $f=1MHz$
C_{OSS}	Output capacitance	-	26	-		
C_{RSS}	Reverse capacitance	-	0.9	-		
$C_{o(er)}$	Effective output capacitance (energy related)	-	48	-	pF	$V_{GS}=0V$, $V_{DS}=0$ to 400V
$C_{o(tr)}$	Effective output capacitance (time related)	-	68	-	pF	$V_{GS}=0V$, $V_{DS}=0$ to 400V
Q_{OSS}	Output Charge	-	27	-	nC	$V_{GS}=0V$, $V_{DS}=0$ to 400V
Q_G	Total gate charge	-	2.2	-	nC	$V_{DS}=400V$, $V_{GS}=0$ to 6V, $I_D=1A$
Q_{GS}	Gate-source charge	-	0.2	-		
Q_{GD}	Gate-drain charge	-	0.8	-		
$t_{d(on)}$	Turn-on delay time	-	2.65	-	nS	$V_{DS}=400V$, $V_{GS}=0V$ to 6V, $I_D=2.1A$ $R_{g_on(ext)}=6.8\Omega$ $R_{g_off(ext)}=2.2\Omega$, $L=250\mu H$
$t_{d(off)}$	Turn-off delay time	-	5.72	-		
t_r	Rise time	-	4.51	-		
t_f	Fall time	-	17.10	-		
Reverse Device Characteristics						
V_{SD}	Reverse voltage	-	3	-	V	$V_{GS}=0V$, $I_{SD}=3A$
Q_{RR}	Reverse recovery charge	-	0	-	nC	$I_{SD}=3A$, $V_{DS}=400V$



Electrical Characteristics

$T_j=25^\circ\text{C}$ unless otherwise stated

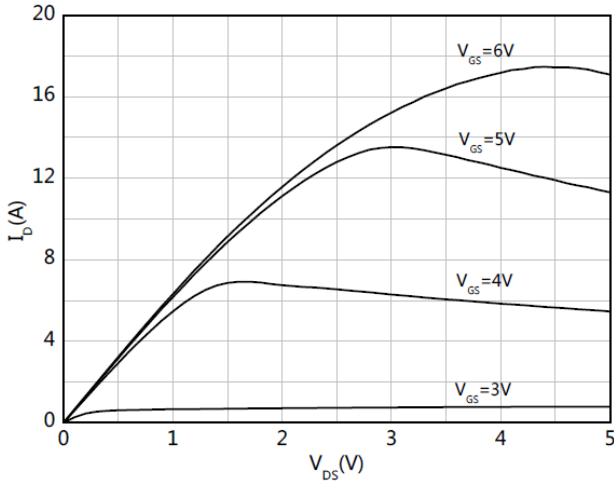


Figure 1. Typical Output Characteristics $T_j=25^\circ\text{C}$

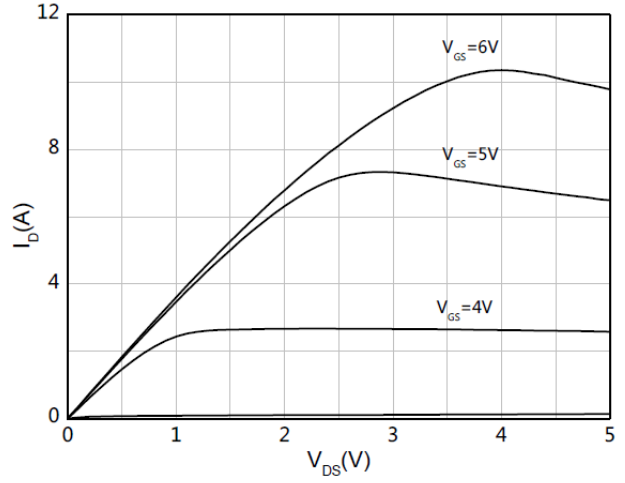


Figure 2. Typical Output Characteristics $T_j=125^\circ\text{C}$

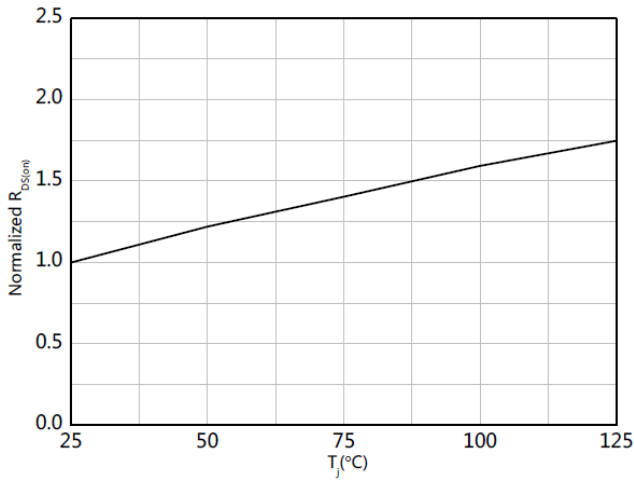


Figure 3. Drain-source On-state Resistance

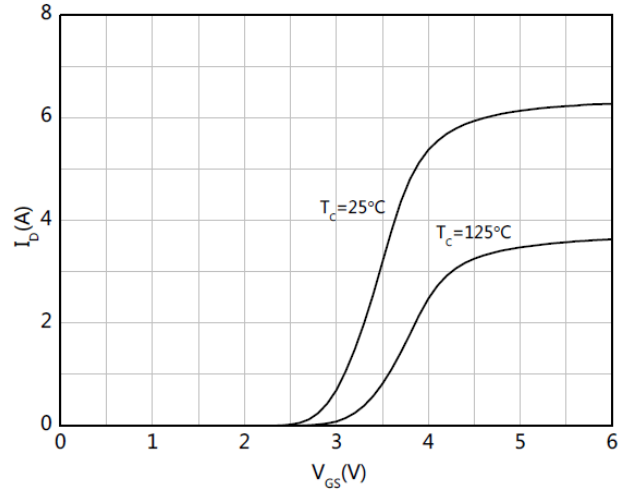


Figure 4. Typical Transfer Characteristics $V_{DS}=1\text{V}$



Electrical Characteristics

$T_j=25^\circ\text{C}$ unless otherwise stated

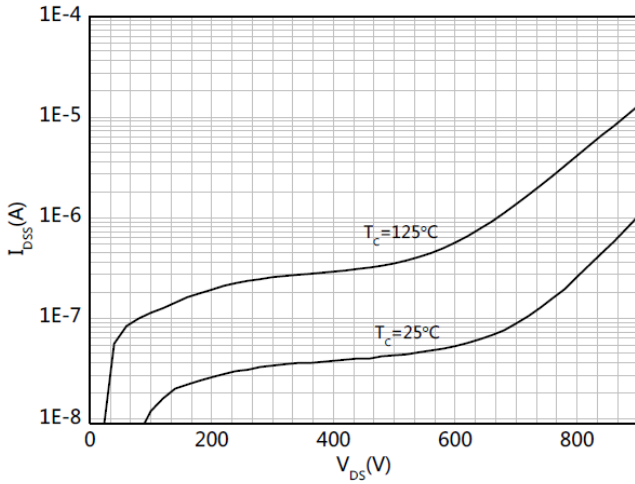


Figure 5. Drain-source Leakage Characteristics

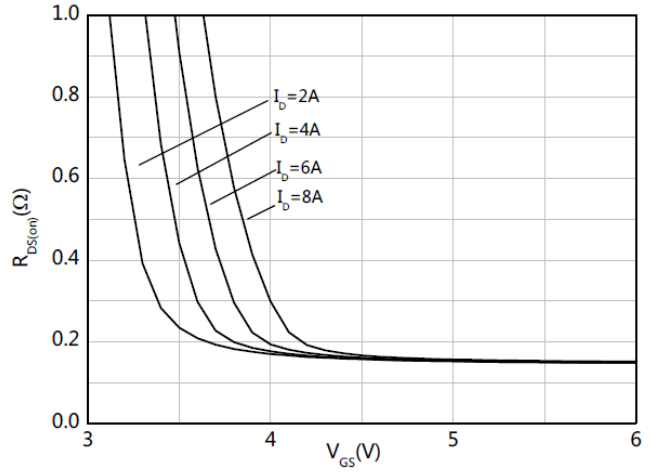


Figure 6. Typical On-state Resistance $T_j=25^\circ\text{C}$

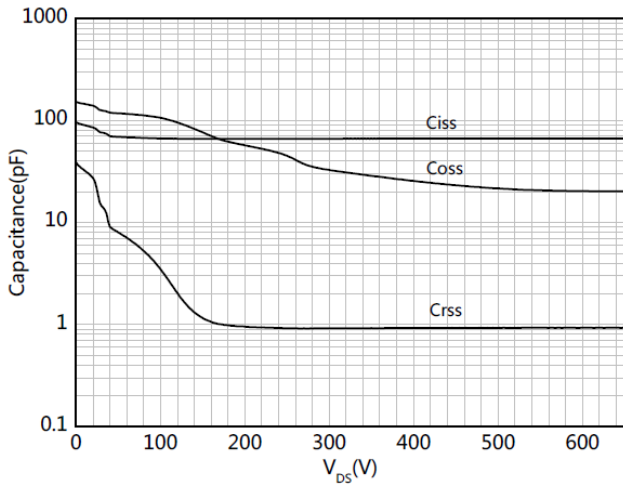


Figure 7. Typical Capacitance $f=1\text{MHz}$

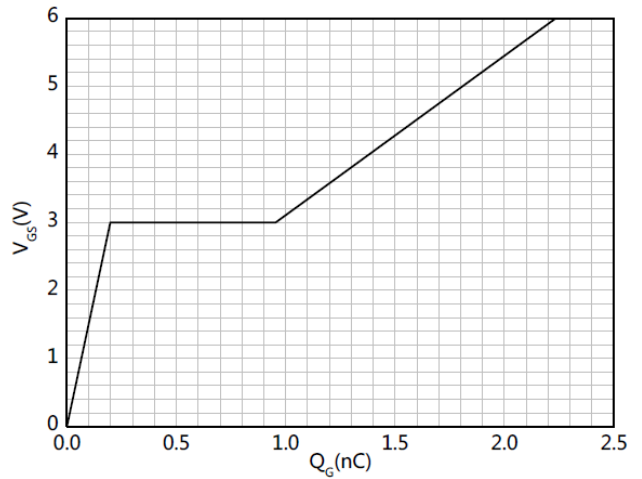


Figure 8. Typical Gate Charge ($V_{DS}=400\text{V}$, $I_D=1\text{A}$)



Electrical Characteristics

$T_j=25^\circ\text{C}$ unless otherwise stated

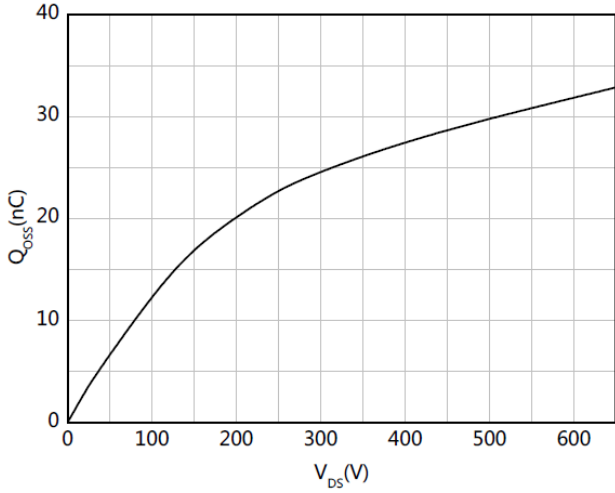


Figure 9. Typical Output Charge $f=1\text{MHz}$

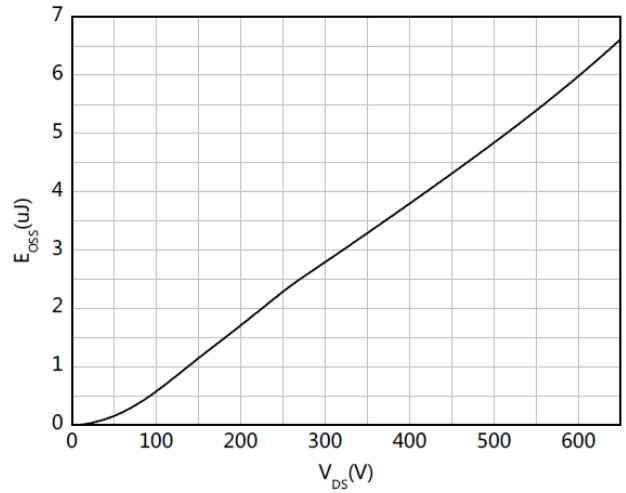


Figure 10. Typical Coss Stored Energy $f=1\text{MHz}$

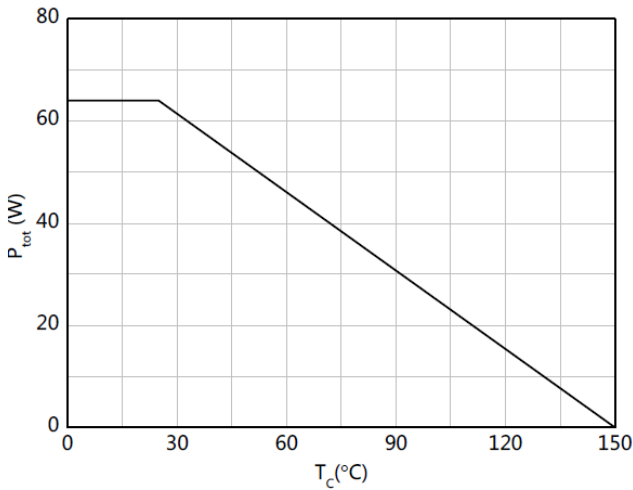


Figure 11. Power Dissipation

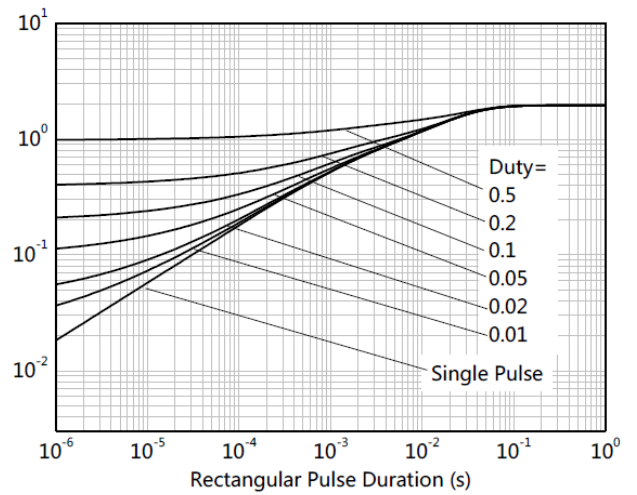


Figure 12. Transient Thermal Impedance

Electrical Characteristics

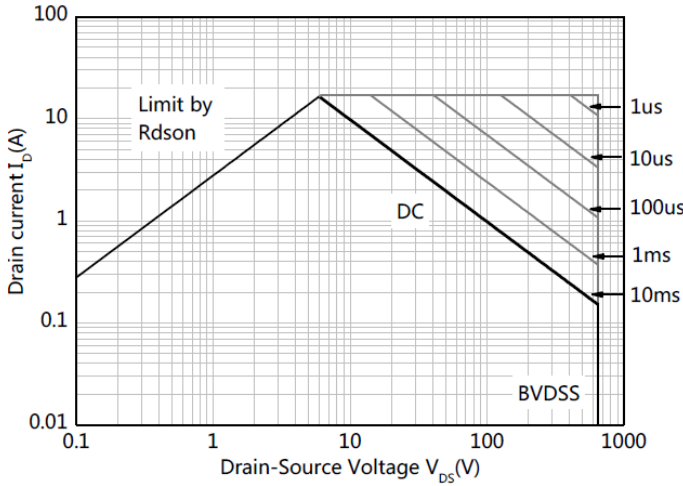


Figure 13. Safe Operation Area $T_c=25^\circ\text{C}$

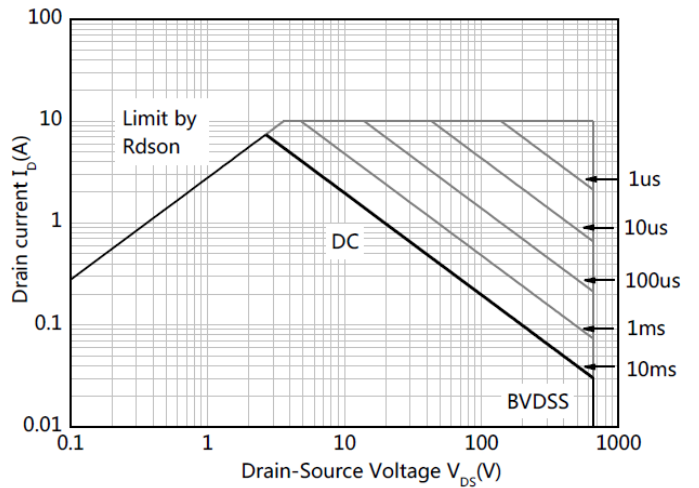


Figure 14. Safe Operation Area $T_c=125^\circ\text{C}$

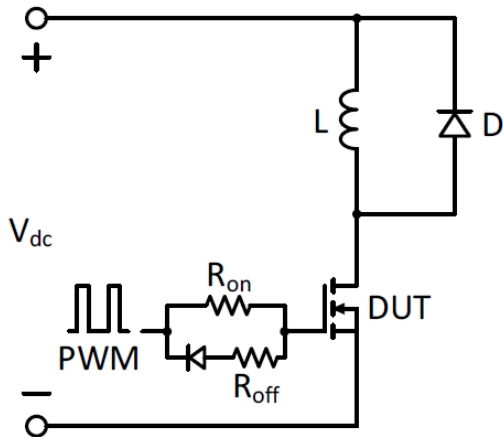


Figure 15. Switching Times With Inductive Load

$V_{DS}=400\text{V}$, $V_{GS}=0\text{V to }6\text{V}$, $I_D=2.1\text{A}$,
 $R_{G-on(ext)}=6.8\Omega$, $R_{G-off(ext)}=2.2\Omega$, $L=250\mu\text{H}$

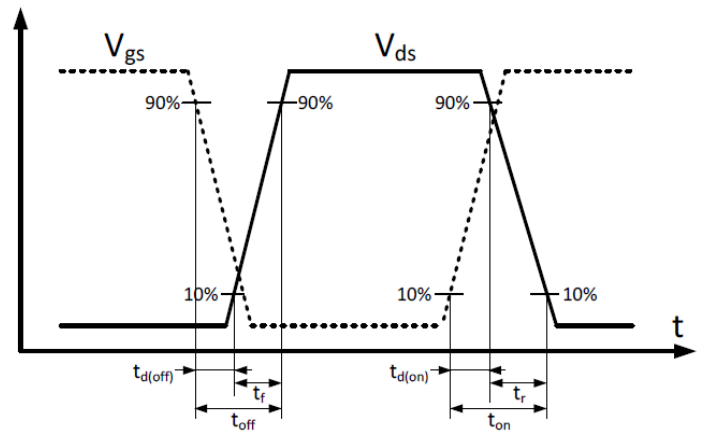


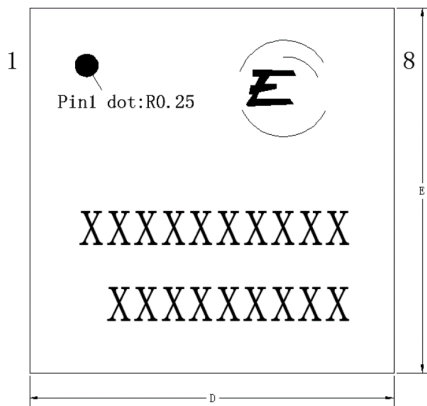
Figure 16. Switching Times With Waveform



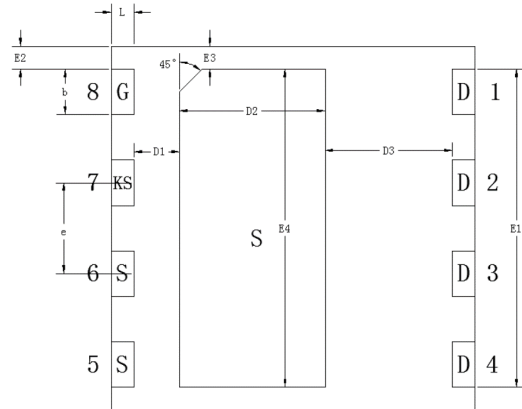
PACKAGE DIMENSIONS

DFN8*8-8L-A

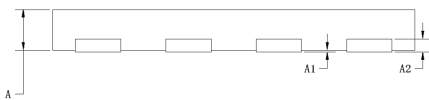
Top view



Bottom view



Side view(left/right)



Symbol	Min. (mm)	Mean. (mm)	Max. (mm)
A	0.80	0.90	1.00
A1	0	0.02	0.05
A2	0.203REF		
D	7.9	8	8.1
E	7.9	8	8.1
D1	0.9	1	1.1
D2	3.1	3.2	3.3
D3	2.7	2.8	2.9
E1	6.9	7	7.1
E2	0.4	0.5	0.6
E3	0.4	0.5	0.6
E4	6.9	7	7.1
e	1.9	2	2.1
b	0.9	1	1.1
L	0.4	0.5	0.6